



## MOSFETs Silicon 450V N-Channel MOS

## ■ Applications

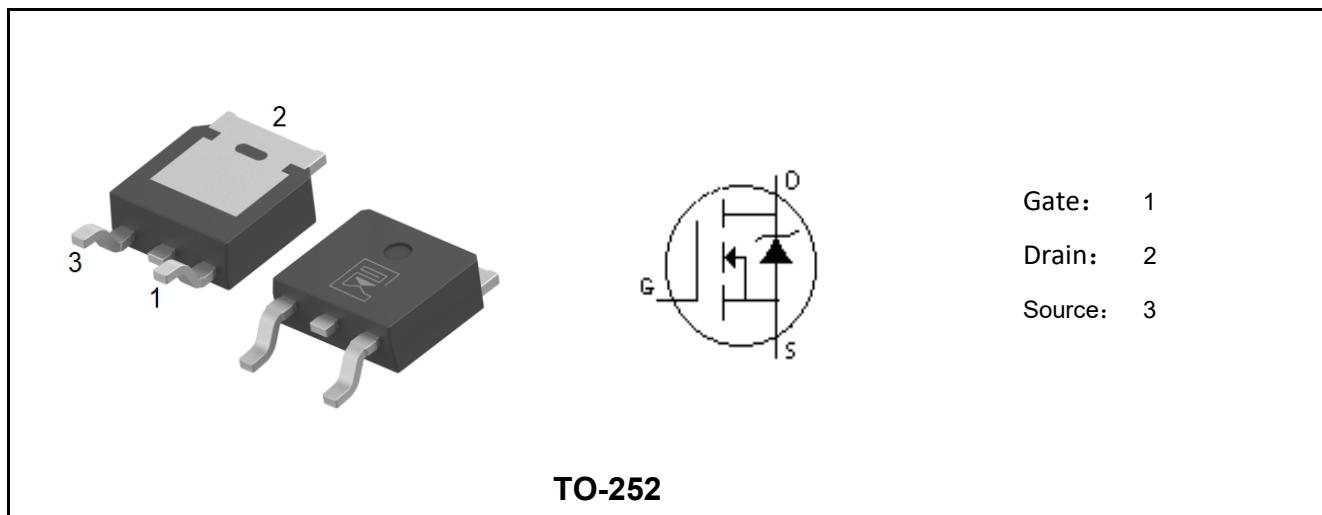
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

## ■ Features

- Low Crss
- Ultra Low Gate Charge
- Fsat switching capability
- RoHS Compliant
- 100% UIS and RG Tested

## ■ Product Summary

$V_{DS}$	450	V
$I_D$	11	A
$R_{DS(ON),Typ}@10V$	0.42	$\Omega$
$Q_g$	30	nC



Marking	Package	Packaging	Min. package quantity
MKIRF11N45B	TO-252	Tape & Reel	3000



**■ Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	450	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current T <sub>c</sub> =25°C (Note 1)	I <sub>D</sub>	11	A
Continuous Drain Current T <sub>c</sub> =100°C (Note 1)		6.5	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	44	A
Total Dissipation	P <sub>D</sub>	113	W
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	E <sub>AS</sub>	333	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

**■ Thermal Characteristics**

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R <sub>θJC</sub>	1.1	°C/W
Maximum Junction-to-Ambient	R <sub>θJA</sub>	60	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub>=100V, T<sub>ch</sub>= 25°C(initial), I<sub>AS</sub>=36.5A, R<sub>g</sub>=25Ω, L=0.5mH.

Note 3: The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





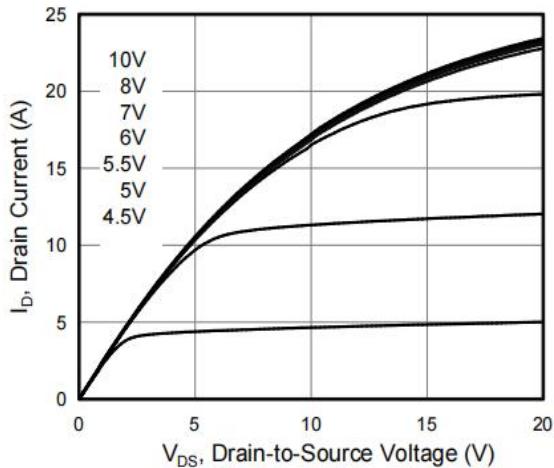
■ Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	B <sub>V<sub>DSS</sub></sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	450	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =450V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	3	4	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.5A	-	0.42	0.45	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	1352	-	pF
Output Capacitance	C <sub>oss</sub>		-	122	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	2.9	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	1.6	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =225V, I <sub>D</sub> =11A, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω	-	29	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	48	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	56	-	ns
Turn-Off Rise Time	t <sub>f</sub>		-	35	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =360V, I <sub>D</sub> =11A, V <sub>GS</sub> =10V	-	30	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	8.2	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	9.1	-	nC
<b>Source-Drain Characteristics</b>						
Max. Diode Forward Cuurent	I <sub>S</sub>		-	-	11	A
Max. Pulsed Forward Cuurent	I <sub>SM</sub>		-	-	44	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-	0.87	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =400V, I <sub>F</sub> =10A, di/dt=100A/us	-	277	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	2.2	-	μC

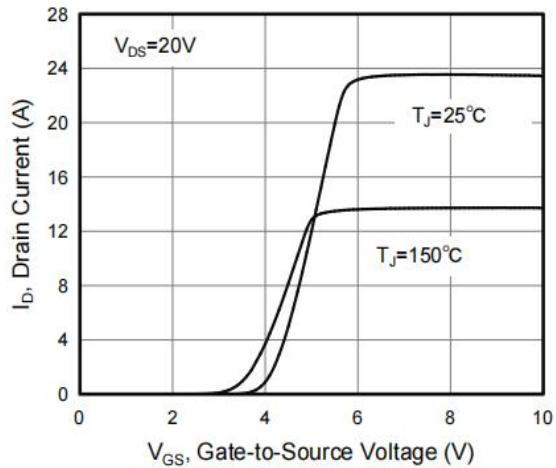




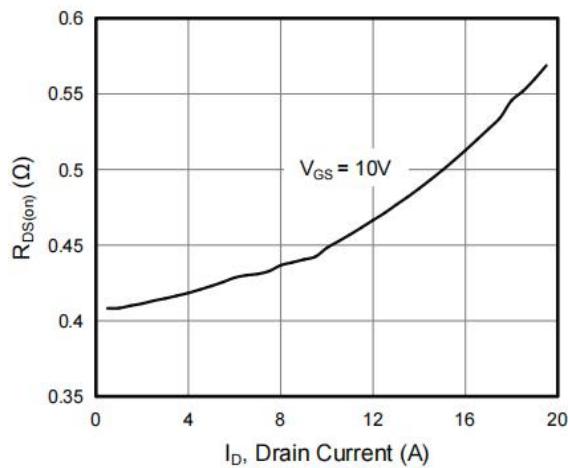
## ■ Characteristics Curves



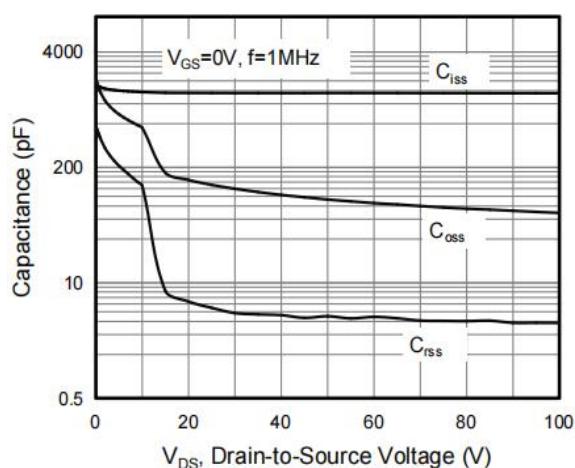
Output Characteristics



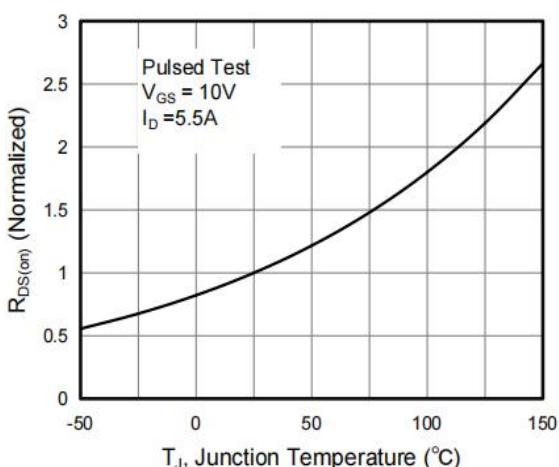
Transfer Characteristics



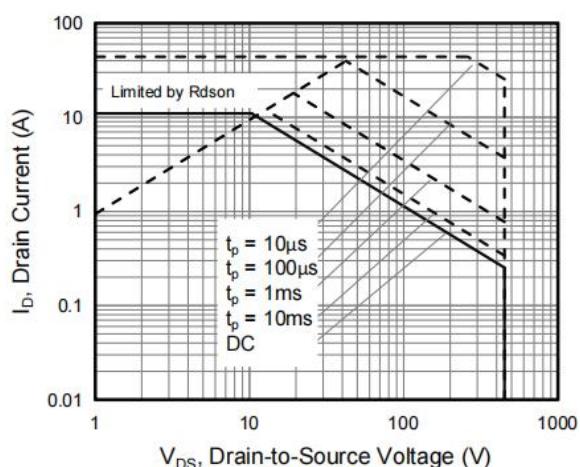
On Resistance Vs Drain Current



Capacitance



Rdson-JunctionTemperature



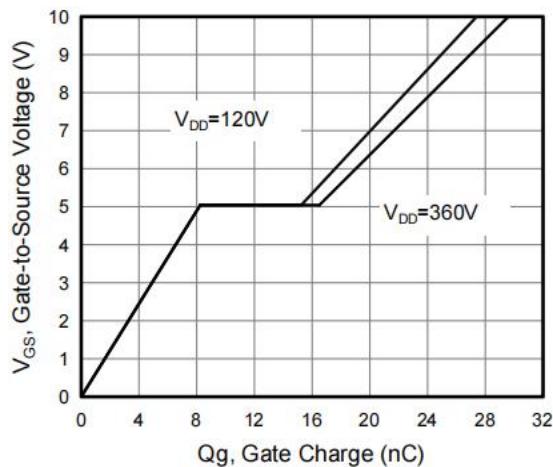
Safe Operating Area



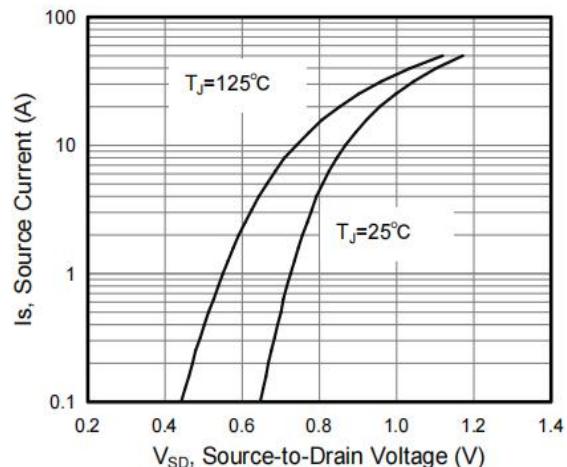


**MC-Power**

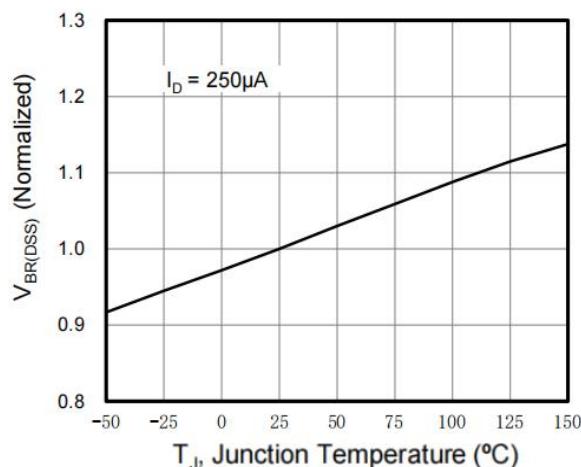
**MKIRF11N45B**



**Gate Charge Waveform**



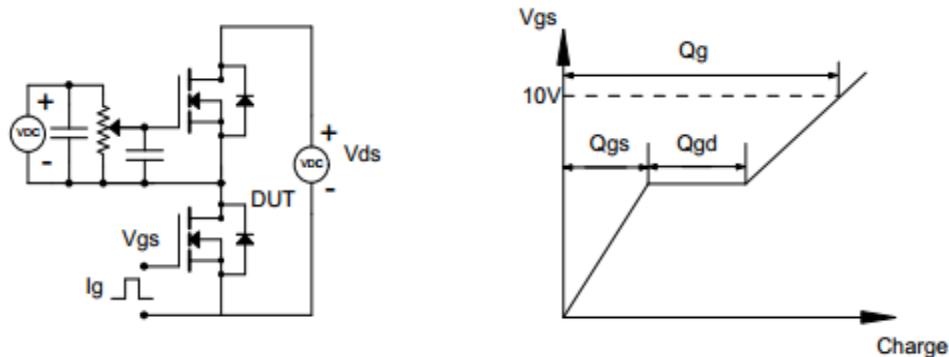
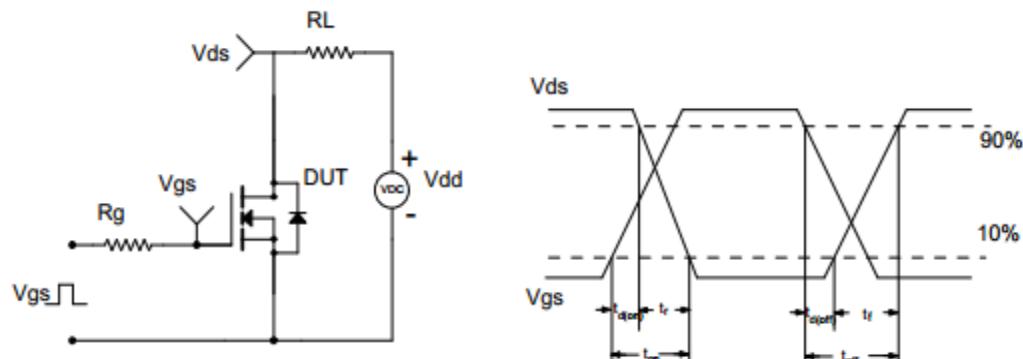
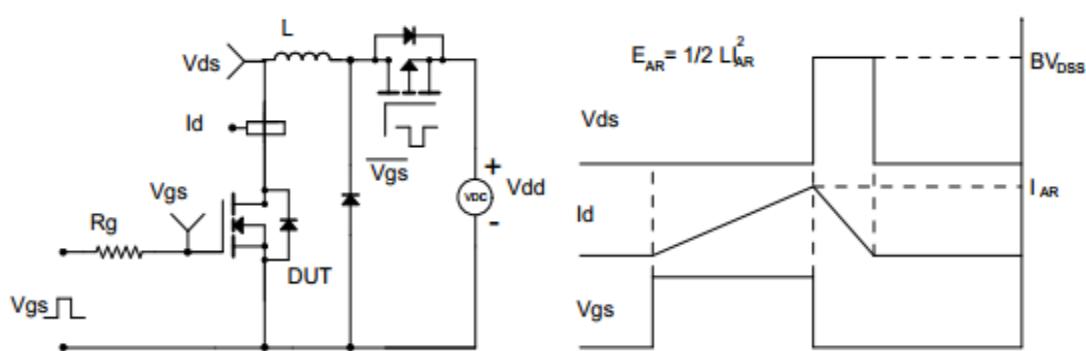
**Source-Drain Diode Forward Voltage**



**Breakdown Voltage Vs Junction Temperature**

Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



**■ Test Circuit & Waveform****Gate Charge Test Circuit & Waveform****Resistive Switching Test Circuit & Waveform****Unclamped Inductive Switching (UIS) Test Circuit & Waveform**



## ■ TO-252 Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	2.10		2.50	E	5.80		6.30
B	0.80		1.25	e1	2.25	2.30	2.35
b	0.50		0.85	e2	4.45		4.75
b1	0.50		0.90	L1	9.50		10.20
b2	0.45		0.60	L2	0.90		1.45
C	0.45		0.60	L3	0.60		1.10
D	6.35		6.75	K	-0.1		0.10
D1	5.10		5.50				

